Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 3 X 0.65 (1.59 X 1.89 EP)
Lead Count	8
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Organic materials	Bisphenol-A Epoxy Resin	25068-38-6	4.68E-03	55.00	550000	34.16	341642
Organic materials	Tetra Hydrophthalic Anhydride	85-43-8	2.55E-03	30.00	300000	18.64	186350
Organic materials	Tris(2,3-Epoxy Propyl) Isocryanurate	2452-62-9	1.11E-03	13.00	130000	8.08	80752
Organic materials	2,6-Ditert.butyl-4-Methyl phenol	128-37-0	1.70E-04	2.00	20000	1.24	12423
Subtotal			8.51E-03	100.00	1000000	62.12	621168

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.53 E-03	97.50	975000	33.10	330960
Copper & its alloys	Iron	7439-89-6	1.09 E-04	2.35	23500	0.80	7977
Copper & its alloys	Zinc	7440-66-6	5.58 E-06	0.12	1200	0.04	407
Copper & its alloys	Phosphorus	7723-14-0	1.40 E-06	0.03	300	0.01	102
Subtotal			4.65 E-03	100.00	1000000	33.94	339447

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.42 E-05	90.9	909091	0.40	3954
Precious metals	Palladium	7440-05-3	4.71 E-06	7.9	79051	0.03	344
Precious metals	Gold	7440-57-5	7.07 E-07	1.2	11858	0.01	52
Subtotal			5.96 E-05	100.00	1000000	0.43	4349

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-04	100.0	1000000	0.73	7299

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.50 E-04	100.0	1000000	2.55	25547

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	9.60 E-06	32.00	320000	0.07	701
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-2	1.05 E-05	35.00	350000	0.08	766
Other organic materials	Epoxy Resin	TS ref# 10114/TS ref# 10105	9.00 E-06	30.00	300000	0.07	657
Others	Amine	TS ref# 10039	9.00 E-07	3.00	30000	0.01	66
Subtotal			3.00 E-05	100.0	1000000	0.22	2190

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.37 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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